

GMM – Fachgruppe 1.2.3 Abscheide- und Ätzverfahren

22. Workshop

Wednesday, December 11, 2019

Fraunhofer IISB, Schottkystraße 10, 91058 Erlangen, Germany

10:00 **Welcome**

Werner Robl, *Infineon Technologies AG, Regensburg, Germany*
Georg Roeder, *Fraunhofer IISB, Erlangen, Germany*

Electrochemical Deposition (ECD)

10:15 **Copper Metallization for More-than-Moore Applications**

Werner Robl, *Infineon Technologies AG, Regensburg, Germany*

10:40 **Requirements of ECD Cu electrolytes for next Generation Packaging Applications**

Gerhard Steinberger, *Atotech Deutschland GmbH, Berlin, Germany*

11:05 **Coffee Break**

11:35 **DMR - Direct Metal Replenishment for Sn, SnAg and Cu Electroplating Processes**

Nick Maser, *ancosys GmbH, Pliezhausen, Germany*

12:00 **Cobalt Metallization on 300 mm Wafer: From CVD to Plating**

Lukas Gerlich, *Fraunhofer Institute for Photonic Microsystems IPMS –
Business Unit Center Nanoelectronic Technologies (CNT), Dresden, Germany*

12:25 **Multiscale Investigation of the Seed Layer Impact on the Electrochemical Deposition**

Marcus Wislicenus, *Fraunhofer Institute for Photonic Microsystems IPMS –
Business Unit Center Nanoelectronic Technologies (CNT), Dresden, Germany*

12:50 **Lunch Break**

New Developments in Deposition and Etching

14:00 **Simulation of Copper Deposition by ECD and PVD**

Andreas Zienert, *Fraunhofer ENAS, Chemnitz, Germany*

14:25 **Advances in Doped AlN Deposition Techniques for Next Generation PiezoMEMS**

Anthony Barker, *SPTS Technologies Ltd., United Kingdom*

14:50 **Coffee Break**

15:20 **Development and Scale-up of Alloy Sputter Targets for PiezoMEMS and STT-MRAM Applications**

Martin Schlott, *Materion Advanced Materials Germany GmbH, Alzenau, Germany*

15:45 **Ecofluor – Environmentally-friendly PECVD chamber cleaning?**

Michael Enzelberger-Heim¹, Robert Wieland², ¹*Texas Instruments Deutschland GmbH, Freising, Germany*, ²*Fraunhofer-Einrichtung für Mikrosysteme und Festkörper-Technologien EMFT, Munich, Germany*

16:10 **Quicker from R&D to Line – A „Smart Experiments“ Approach**

Sabrina Anger, *Fraunhofer Institute for Integrated Systems and Device Technology IISB, Erlangen, Germany*

16:35 **Final Discussion, Closing Remarks**

16:45 **End of Workshop**
